

BondShield

Copper Adhesive Tape

BondShield Cu is a soft copper foil with a thermosetting polyacrylate resin adhesive, this is available with or without a paper liner. It is suitable for RF/ EMI shielding on motors, cables and components.

Features

- RFI/ EMI shielding aluminium tape
- Conformability fills micro air voids between mating surfaces.
- Solderable as a heating element.
- Moisture resistant
- Electrically conductive

Availability

- Available in standard thicknesses of 0.065
- Supplied on 33M rolls and to specified widths on request.

Benefits

- Provides excellent adhesion between a variety of substrates
- Delivers a permanent mechanical bond with high dielectric strength
- Simple to handle and apply

Recommended Uses

- RFI and eEMI shielding
- Moisture resistance
- Electrically conductive
- Solderable as heating element.

Typical Physical Properties

Property (unit)	Test Method	Bondshield CU
Colour	Visual	Copper
Adhesive Coating		Single Sided
Recommended Curing cycle		1 hour at 150 ° 2hours at 130 °
Temperature Resistance(°C)	In House	155

Electrical and Mechanical Information

Property (unit)	Test Method	BondShiled Cu
Adhesive Strength N/cm	ASTM D-1002	4.5
Tensile Strength (N/cm)	ASTM 412	40.0
Supporting Base		Soft Copper Foil
Base Thickness (mm)		0.040
Total Thickness (mm)		0.065

